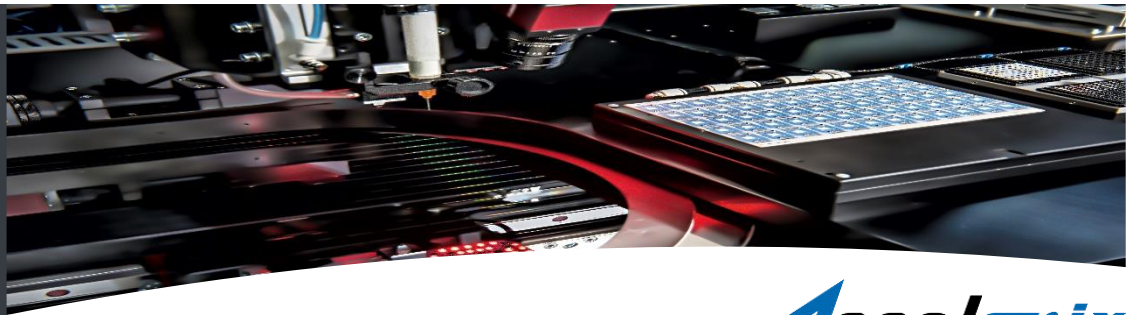




T-6000-L/G



- Best bonding performance in the market
- Designed for tomorrow's semiconductor needs
- One machine, unlimited bonding processes
- Made in Germany 

The T-6000-L/G DIE Bonder combines precision with customization and speed.

It is built on a granite gantry to achieve the highest level of bonding accuracy.

The ultimate bonding platform from prototyping to volume production

The T-6000-L/G the unmatched level of modularity and flexibility.

Unique manual mode for instant DIE bonding.

Technical Data

Placement Area with Wafer
Wafer Size
Placement Area w/o Wafer
Z-Movement
Chip Rotation max.
Bond Force Range
Axis Speed
Placement Accuracy
Axis Resolution
Min./Max. Component Size

300 mm x 400 mm
2" – 8" (Ring & Frame)
470 mm x 420 mm
100 mm
up to 360°
10 g – up to 10.000 g *
up to 1.8 m/sec
2.5 µm @ 3 sigma
XYZ: 0.01 µm, Theta: 0.01°
80 µm – 100 mm **

* Higher bond force on request

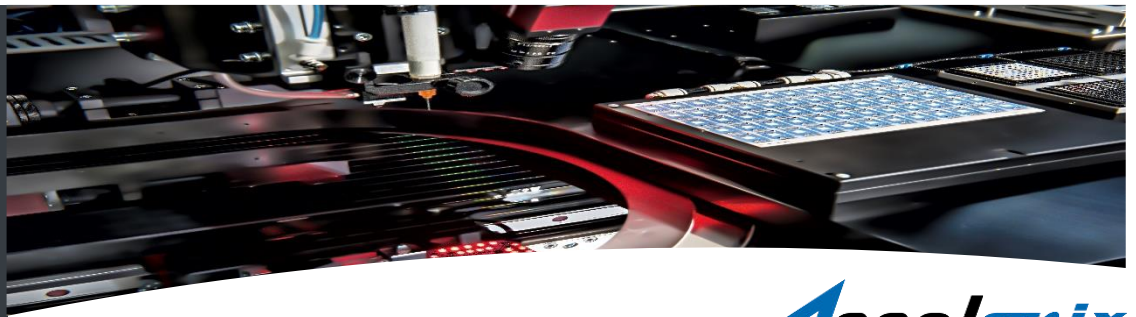
** Other dimensions on request | Note: All specifications are subject to change without notice

Contact

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info@tresky.de

For more information
about our products or
services please visit our
website www.tresky.de



DIE Attach Technologies

- Micro Assembly
- Eutectic Bonding
- Stamping
- Ultrasonic Bonding
- Flip Chip Bonding
- Thermosonic Bonding
- Thermocompression Bonding
- Flux Dipping
- Adhesive Bonding
- DIE Stacking

Applications (Customer Specific)

- DAF / DTF Bonding
- Multi DIE Bonding
- MEMS
- SMD Bonding
- 3D Packaging (SiP)
- Laser Bar Stacking
- Glas Frit Bonding
- TO Header Bonding
- Vcsel Bonding
- RFID Assembly
- DIE Sorting

Modules & Options

- Wafer Table with DIE Ejector
- UV Indexer
- WRGB Light
- Heating Plates
 - Up to 450°C
 - Ramp rates up to 60 K/s
- Inert Gas Protection
- Pre-heated Inert Gas
- Conveyor / Magazine Lifter
- Automatic Tool Change
- Dispensing Options
- Inline Production
- Stamping Unit
- Tool Heating
- Feeder Unit
- Uplooking Camera
- ID Scanner
- DIE Flipping Unit

Features

- Manual Mode
- Multichip Application Capability
- Post Bond Inspection
- Software integrated temp. Control
- Wafer Mapping
- OCR
- Traceability
- MES
- Automatic Dispense Needle Calibration
- Customer Specific Workspace
- Scrubbing
- Pattern Recognition Methods
- Deep Access Bonding (15 mm)
- Automatic Wafer Change
- Preform Cutter

Contact

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